

SRI International

Monthly Status Report • December 2010
Covering the Period 1 December through 31 December 2010

POWER MEMS DEVELOPMENT

Contract N00014-09-C-0252

Submitted in accordance with Deliverable A001 - Monthly Technical and Financial
SRI Project P19063

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Report Documentation Page			Form Approved OMB No. 0704-0188		
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1. REPORT DATE JAN 2011	2. REPORT TYPE		3. DATES COVERED 00-00-2011 to 00-00-2011		
4. TITLE AND SUBTITLE Power Mems Development			5a. CONTRACT NUMBER		
			5b. GRANT NUMBER		
			5c. PROGRAM ELEMENT NUMBER		
6. AUTHOR(S)			5d. PROJECT NUMBER		
			5e. TASK NUMBER		
			5f. WORK UNIT NUMBER		
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) SRI International,333 Ravenswood Ave,Menlo Park,CA,94025			8. PERFORMING ORGANIZATION REPORT NUMBER		
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES)			10. SPONSOR/MONITOR'S ACRONYM(S)		
			11. SPONSOR/MONITOR'S REPORT NUMBER(S)		
12. DISTRIBUTION/AVAILABILITY STATEMENT Approved for public release; distribution unlimited					
13. SUPPLEMENTARY NOTES					
14. ABSTRACT					
15. SUBJECT TERMS					
16. SECURITY CLASSIFICATION OF:			17. LIMITATION OF ABSTRACT Same as Report (SAR)	18. NUMBER OF PAGES 4	19a. NAME OF RESPONSIBLE PERSON
a. REPORT unclassified	b. ABSTRACT unclassified	c. THIS PAGE unclassified			

MICROELECTROMECHANICAL SYSTEM (MEMS) RESETTABLE CIRCUIT BREAKER (TASK 1.1) AND MEMS SWITCH FOR DC-DC VOLTAGE CONVERTERS (TASK 1.2)

Task 1.1 Contributors: Sunny Kedia, Weidong Wang, Susana Stillwell

Task 1.1 Deliverable: 10 prototype packed MEMS-based resettable circuit breakers for testing and analysis in the Office of Naval Research (ONR) laboratories.

Task 1.2 Contributors: Sunny Kedia, Shinzo Onishi, Scott Samson, Drew Hanser

Task 1.2 Deliverable: Functional MEMS-based DC-DC converter in a vacuum package.

Summary: This month in Task 1.1, we processed wafers with the revised Metal 3 and Dielectric masks. We completed the processing of the double-side-polished (DSP) wafer; however, the silicon-on-insulator (SOI) wafer is on hold due to deep reactive ion etching (DRIE) processing issues.

In Task 1.2, we processed wafers with the new pre-sputter metal deposition process. We diced chips from these wafers and released them using both using hydrogen fluoride (HF) and buffered-oxide-etch (BOE) processes. The metals were unaffected in both processes. We then flip-chip bonded the chips and tested the device for switch operation. During testing, we found that all of the actuating silicon (Si) structures that were tested moved toward the Si substrate instead of the glass electrode and remained stuck to the Si substrate. Further analysis showed switches that were not tested remained released, indicating this occurred as a result of the testing. These data suggest that during testing there is an electric potential established between the plate and the Si substrate that allows the plate to move toward the substrate instead of the electrode on the glass substrate. A 1- μm gap between the plate and the substrate allows a small potential to move the plate toward the substrate. We believe this potential occurs due to large contact resistance between the metal contact pad and the substrate, resulting in a voltage at the substrate that is sufficiently large to move the plate.

To address this issue, we are designing a mask to etch the Si substrate in the vicinity of the plate to eliminate the substrate potential below the plate.

DIAMOND HEAT SPREADER OR HEAT SINK FOR HIGH-POWER MEMS SWITCH APPLICATIONS (TASK 1.3)

Contributors: Priscila Spagnol, Shinzo Onishi, Drew Hanser, Weidong Wang, Sunny Kedia, John Bumgarner

Deliverable: Prototype device fabricated on a thin-film diamond heat spreader layer and individual samples of diamond on Si or other suitable substrates for material evaluation.

Summary: No work was done this month on Task 1.3.

POSITRON TRAPPING AND STORAGE (TASK 2)

Contributors: Ashish Chaudhary, Friso van Amerom, Tim Short

Deliverable: A minimum of four MEMS-based trap structures for radio frequency (RF) trapping of electrons.

Summary: We assembled the test set-up using the new aluminum (Al) flanges to shield high voltages and repeated experiments to determine if electrons were trapped.

To improve the injection efficiency of the electrons in the trap, a 180° out-of-phase RF potential was generated using a balun and applied to the opposite RF electrodes. A pulsed scheme was used on both Mesh 1 and Endcap 1 to slow the electrons down. We varied the biasing at the electron source microchannel plate (MCP) backside from 0 to 15 volts to shift the energy of the generated electrons. No signal was observed that would indicate trapping of electrons.

FINANCIAL STATUS

R&D Status Report

Program Financial Status

15 July 2009 through 1 January 2011

Contract Item No.	Current Funding	Current Period Expenses	Cumulative Expenses	% Budget Complete
0001	\$1,829,849	\$30,545	\$1,571,596	86%
Project Commitments		(2,059)	211,875	
Total	\$1,829,849	\$28,486	\$1,783,471	

Based on currently authorized work:

Is current funding sufficient for the current fiscal year (FY)? (Explain if NO) **Yes**

What is the next FY funding requirement at current anticipated levels **N/A (base fully funded)**